

In the Claims:

1-17 (Cancelled)

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18. (New) A solid-state radiographic sensor device, comprising:

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a first detector portion, including

a solid-state detector having an anode at a first surface thereof and a cathode at a second surface opposite said first surface,

associated detector circuitry for developing electrical signals in response to radiation detection events in said solid-state detector, said detector circuitry having at least one surface area suitable for accommodating an electrical contact connection point,

a high-voltage contact point provided on said at least one surface,

an insulated conductor electrically coupled at one end thereof to said high-voltage contact point and at another end thereof to said cathode, and

a signal connection interface; and

a second signal processing portion connected to said first detector portion via said signal connection interface, including

signal processing circuitry that receives signals from said associated detector circuitry via said signal connection interface, and

a separable high-voltage interconnect coupled at one end thereof to a voltage source, and extending from said second signal processing portion so as to make contact with said high-voltage contact point upon connection of said second signal processing portion with said first detector portion, to provide a voltage to said cathode sufficient to properly bias said cathode for proper operation of said sensor device.

19. (New) The solid-state radiographic sensor device of claim 18, further including a contact biasing device for biasing said separable high-voltage interconnect against said high-voltage contact point upon connection of said second signal processing portion with said first detector portion.

20. (New) The solid-state radiographic sensor device of claim 18, wherein said separable high-voltage interconnect extends from said second signal processing portion

in such manner so as to be movable with respect to a plane of said second signal processing portion.

21. (New) The solid-state radiographic sensor device of claim 19, wherein said contact biasing device for biasing said separable high-voltage interconnect against said high-voltage contact point comprises a spring.

22. (New) The solid-state radiographic sensor device of claim 18, wherein said high-voltage contact point comprises a metallic pad.

23. (New) A method of providing a high voltage to a cathode of a solid-state detector of a radiographic sensor device, comprising the steps of:

providing a high-voltage contact point on a surface of a first detector portion of said radiographic sensor device,

providing an insulated conductor on said solid-state detector that electrically couples said high-voltage contact point to said cathode,

providing an elongated high-voltage interconnect that extends from a surface of a second signal processing portion of said radiographic sensor device so as to make electrical contact with said high-voltage contact point upon connection of said first detector portion to said second signal processing portion in a manner that does not require precise alignment of said interconnect to said high-voltage contact point.

24. (New) The method of claim 23, further comprising the step of biasing said elongated high-voltage interconnect in a direction away from said second signal processing portion.

25. (New) The method of claim 24, wherein said step of biasing comprises the step of providing a contact biasing device for biasing said separable high-voltage interconnect against said high-voltage contact point.

26. (New) The method of claim 25, wherein said contact biasing device comprises a spring.

27. (New) The method of claim 23, wherein said step of providing a high-voltage contact point comprises the step of providing a metallic pad.